

# SOT770-1

plastic thermal enhanced thin shrink small outline package; 8 leads; body width 3 mm; exposed die pad

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HTSSOP8
<b>Package type industry code</b>	HTSSOP8
<b>Package style descriptive code</b>	HTSSOP (thermal enhanced thin shrink small outline package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-5-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A <sub>2</sub>	package height	0.75	-	0.85	0.95	mm
n <sub>2</sub>	actual quantity of termination	-	-	8	-	

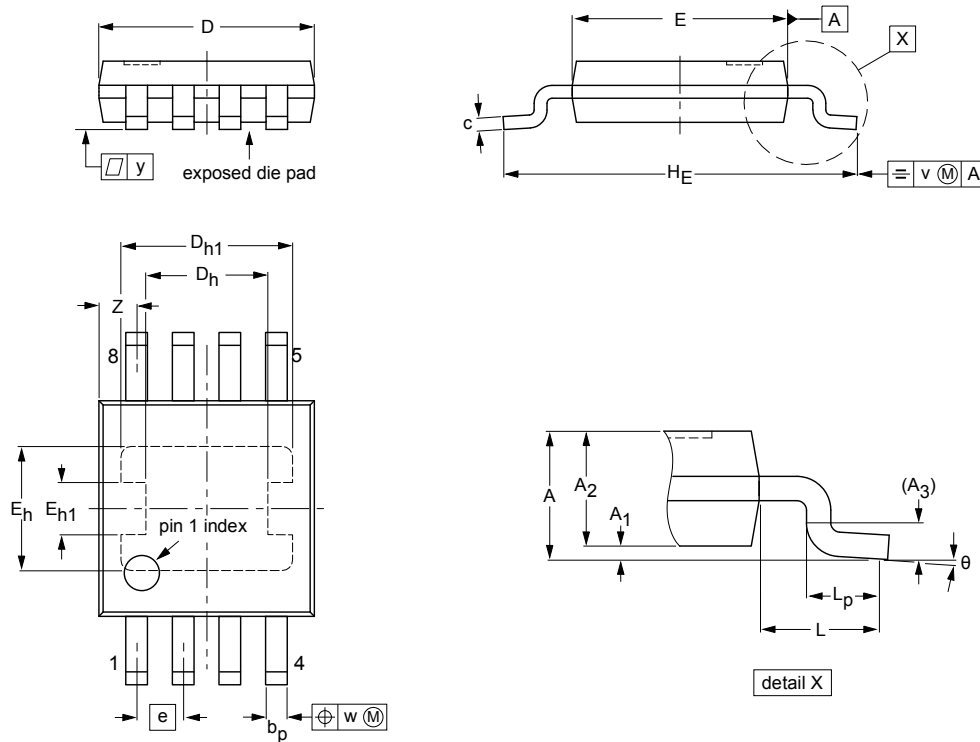


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2. Package outline

HTSSOP8: plastic thermal enhanced thin shrink small outline package; 8 leads; body width 3 mm; exposed die pad

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	D <sub>h1</sub>	E <sup>(2)</sup>	E <sub>h</sub>	E <sub>h1</sub>	e	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.75	0.25	0.38 0.22	0.23 0.08	3.1 2.9	1.8 1.6	2.4	3.1 2.9	1.83 1.63	0.73	0.65	5.1 4.7	0.95	0.8 0.4	0.2	0.13	0.1	0.70 0.35	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT770-1		---			02-05-14

Fig. 1. Package outline HTSSOP8 (SOT770-1)

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### 3. Soldering

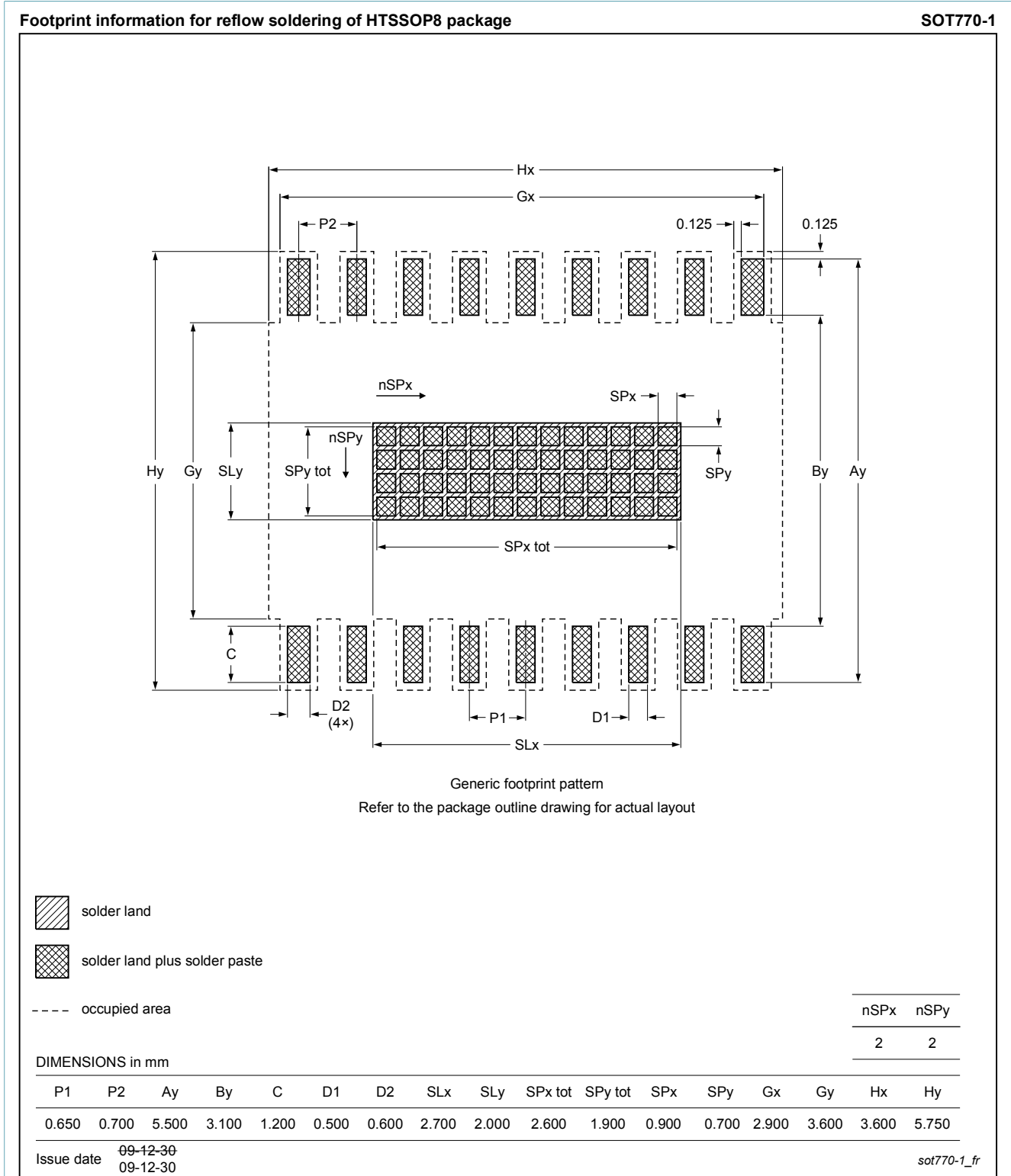


Fig. 2. Reflow soldering footprint for HTSSOP8 (SOT770-1)

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## 4. Legal information

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